PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6306999

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MARIE TOYOSHIMA	08/07/2020
TAISHIN YOSHIDA	08/07/2020

RECEIVING PARTY DATA

Name:	e: SONY SEMICONDUCTOR SOLUTIONS CORPORATION	
Street Address:	Address: 4-14-1 ASAHICHO, ATSUGI-SHI	
City:	KANAGAWA	
State/Country:	JAPAN	
Postal Code:	243-0014	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16961859

CORRESPONDENCE DATA

Fax Number: (414)277-0656

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 414-271-6560

Email: DCipdocket@michaelbest.com

Correspondent Name: MICHAEL BEST & FRIEDRICH LLP (SONY)

Address Line 1: 790 N WATER ST Address Line 2: SUITE 2500

Address Line 4: MILWAUKEE, WISCONSIN 53202

ATTORNEY DOCKET NUMBER: 880005-6637-US01	
NAME OF SUBMITTER: CHRISTOPHER M. TOBIN	
SIGNATURE:	/Christopher M. Tobin/
DATE SIGNED:	09/18/2020
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2

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PATENT 506260253 REEL: 053821 FRAME: 0578

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	SOLID-STATE IMAGE SENSOR	
As the below	As the below named inventor, I hereby declare that:	
This declarati	The attached ambigation as	
	United States application or PCT international application number PCT/JP2018/042208 filed on2018/11/15	
The above-id	nutified application was made or authorized to be made by me	
WHEREAS,	I am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at	
4-14-1 A	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits according or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;		
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR		
Inventor:	marie toyoshima Dete: August 7, 2020	
Signature:	matie toyoshima	

PATENT REEL: 053821 FRAME: 0579

Attorney Docket No.: Sony Ref. No.: SP371230US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

As the below named inventor, I hereby declare that: This declaration is directed its: Dirited States application or PCT international application number PCT/IP2018/042208	Title of Invention	SOLID-STATE IMAGE SENSOR
Interest to: Interest to the property of the control of the sum of One Dollar (\$1.00), and other good and valuable consideration; and under any interest in the United States and countries for each of any and all foreign experientatives, the entire right, title and interest in some and controls recording and invention. The United States and countries foreign the Patents, and any and all foreign experients of sales and controls for sales and countries foreign the terror of patents. Designs and loasteid Models, and any other international agreements to which the United States and Countries foreign thereto, and all foreign of patents, Designs and loasteid Models, and any other international agreements to which the United States and International Representatives, the entire right, title and interest in any other international agreements to which the United States and in any other international agreements to which the United States and continuations thereof, and in and to any and all priority rights and/or convention rights under the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the states under the states of America adheres, and to any other benefits accruing to reacted to excrete to me with respect to the filting of applications for patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing to reacted to me with respect to the filting of applications for patents are securing of patents in the United States and countries foreign thereto, and I hereby surhorize and request the Commissioner of Patents to issue said United States Letters Patent of the United States and countries foreign thereto, and I hereby authorize and request the Commissio	As the below named inventor, I hereby declare that:	
The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION		The state of the s
Believe that I am the original inventor or an original joint inventor of a claimed inventon in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION		
WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION (hereinafter referred to as ASSIGNEE), is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries; NOW THEREFORE, in consideration of the sum of One Dollar (\$1.90), and other good and valuable consideration; the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all periority rights and/or convention rights under the International Convention for the Protection of Industrial Property. Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States and Fatent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto; And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, anodifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto; And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and	The above-ide	entified application was made or authorized to be made by me.
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designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto; And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense; And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto; And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. LEGAL NAME OF INVENTOR Inventor: TAISHIN YOSHIDA Date: TAISHIN YOSHIDA	of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters	
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application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto; And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. LEGAL NAME OF INVENTOR Inventor: TAISHIN YOSHIDA Date: 1	application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters	
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Inventor: TAISHIN YOSHIDA Date: Quality 7, 2-26		
	LEGAL NA	ME OF INVENTOR
Signature: Josephin Hospitaly	Inventor:	TAISHIN YOSHIDA Date: August 7, 2006
	Signature:	Jushin Yorkida

RECORDED: 09/18/2020

PATENT REEL: 053821 FRAME: 0580